



Electro-Science Laboratories, Inc.

416 East Church Road • King of Prussia, PA 19406-2625, U.S.A

610-272-8000 • Fax: 610-272-6759 • www.ElectroScience.com • Sales@ElectroScience.com

THE MARKET LEADER – PROVEN RELIABILITY

Over 90% of the World's HOS™ (Heaters on Steel) have been made using ESL materials. Millions are being used successfully worldwide.

CERMET SILVER/PLATINUM CONDUCTOR for HOS™ (Heaters on Steel)

9501-CH

The 9501-CH is a low cost, high speed printing silver/platinum conductor material, which exhibits high conductivity and excellent adhesion and solderability. ESL 9501-CH may be used as contact pads for 29XXX Series resistors in HOS™ (Heaters on Steel) applications.

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, 10 rpm, ABZ spindle, 25.5°C±0.5°C)	150±20 Pa·s
BONDING MECHANISM:	Mixed bonded
SHELF LIFE: (20°C)	6 months

PROCESSING

SCREEN MESH/EMULSION:	325/20 µm
LEVELING TIME: (20°C)	10-15 minutes
DRYING AT 125°C:	15 minutes
FIRING TEMPERATURE RANGE: (in air)	850°C-930°C
OPTIMUM:	850°C
TIME AT PEAK TEMPERATURE:	10 minutes

9501-CH 9901-New

ESL Affiliates

Japan: ESL-Nippon Company, Ltd. • Sukegawa Bldg. • 6th floor • 3-4 Yanagibashi 1-chome • Taito-ku • Tokyo 111, Japan • Tel: (011-81)-3-3864-8521 • Fax: (011-81)-3-3864-9270
NipponSales@ESLNippon.com

China: Shanghai Agmet Electro-Science Laboratory Ltd. • Second Floor Bldg. 12A1 • #223 North Fe Te Road • Waigaoqiao Free Trade Zone • Shanghai, China
Tel: (011-86)-21-5866-0497 • Fax: (011-86)-21-5866-0497 • ShanghaiSales@ShanghaiESL.com

Europe: Agmet, Ltd. • 8 Commercial Road • Reading, Berkshire, England RG2 0QZ • Tel: (011-44)-118-987-3139 • Fax: (011-44)-118-986-7331 • Sales@ESLEurope.co.uk

See Caution and Disclaimer on other side.

RATE OF ASCENT/DESCENT:	50°C-60°C/minute
SUBSTRATE FOR CALIBRATION:	96% alumina
THINNER:	ESL 401

TYPICAL PROPERTIES

FIRED THICKNESS: (measured on a 2.0 mm x 2.0 mm pad on 96% alumina)	10.5±2.5 µm
APPROXIMATE COVERAGE:	60-70 cm ² /g
RESISTIVITY:	2-4 mΩ/sq.
PRINTING RESOLUTION: (Line/Space)	250 µm/250 µm
SOLDER WETTABILITY: (RMA flux, 5 sec. dip, 62 Sn/36 Pb/2 Ag, 220°C±5°C)	95%-100%
SOLDER LEACH: (No. of 10 sec. dips to double resistance of 0.25 mm wide x 100 mm long conductor)	5-10 dips
ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag, 220°C±5°C)	
Initial:	68-88 N
Aged 48 hours at 150°C:	58-88 N

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CAUTION: Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapors emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

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